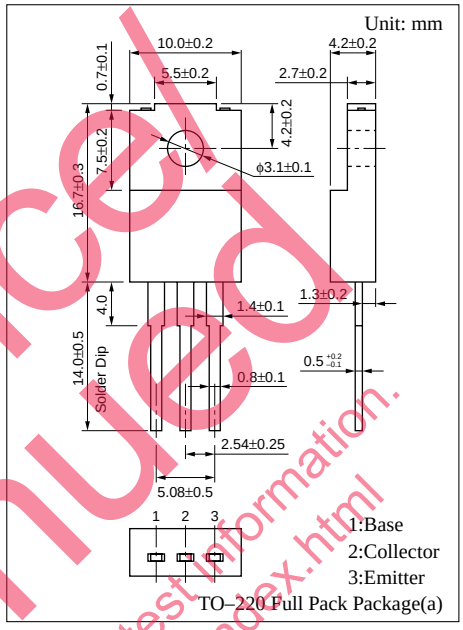
2SD1891

Silicon NPN triple diffusion planar type Darlington

For power amplification

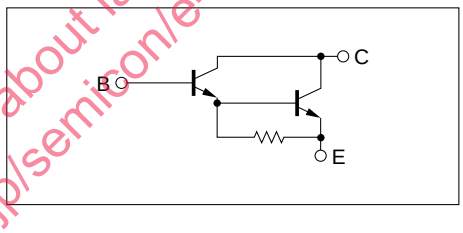
Complementary to 2SB1251



Features

- Optimum for 30W HiFi output
- High foward current transfer ratio h_{FE}: 5000 to 30000
- Low collector to emitter saturation voltage $V_{CE(sat)}$: <3.0V
- Full-pack package which can be installed to the heat sink with one screw

Internal Connection



Absolute Maximum Ratings (T_C=25˚C)

Parameter		Symbol	Ratings	Unit
Collector to base voltage		V_{CBO}	110	V
Collector to emitter voltage		V_{CEO}	90	V
Emitter to base voltage		V_{EBO}	5	V
Peak collector current		I_{CP}	7	A
Collector current		I_C	4	A
Collector power dissipation	T_C=25°C	P_C	40	W
	Ta=25°C		2	
Junction temperature		T_j	150	˚C
Storage temperature		T_{stg}	–55 to +150	˚C

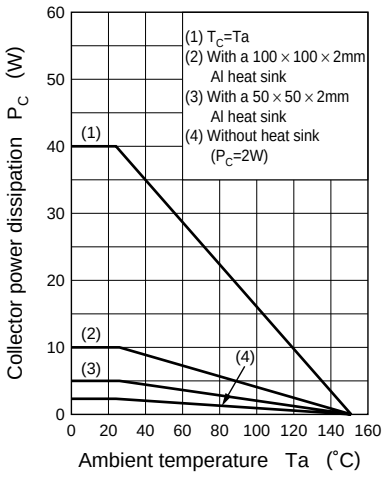
Electrical Characteristics (T_C=25˚C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	V_{CB} = 110V, I_E = 0			100	µA
	I_{CEO}	V_{CE} = 90V, I_B = 0			100	µA
Emitter cutoff current	I_{EBO}	V_{EB} = 5V, I_C = 0			100	µA
Collector to emitter voltage	V_{CEO}	I_C = 30mA, I_B = 0	90			V
Forward current transfer ratio	h_{FE1}	V_{CE} = 5V, I_C = 1A	2000			
	h_{FE2}*	V_{CE} = 5V, I_C = 3A	5000		30000	
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = 3A, I_B = 3mA			3	V
Base to emitter saturation voltage	$V_{BE(sat)}$	I_C = 3A, I_B = 3mA			3	V
Transition frequency	f_T	V_{CE} = 10V, I_C = 0.5A, f = 1MHz		20		MHz
Turn-on time	t_{on}	I_C = 3A, I_{B1} = 3mA, I_{B2} = –3mA, V_{CC} = 50V		2.5		µs
Storage time	t_{stg}			3.0		µs
Fall time	t_f			0.7		µs

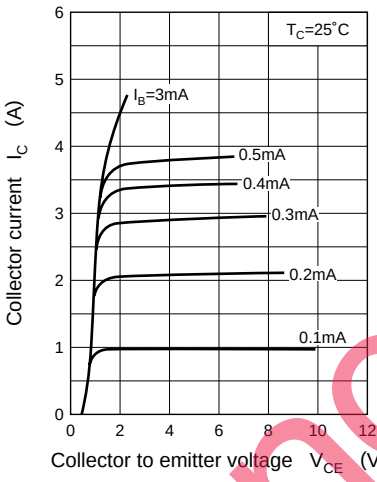
*h_{FE2} Rank classification

Rank	Q	P
h_{FE2}	5000 to 15000	8000 to 30000

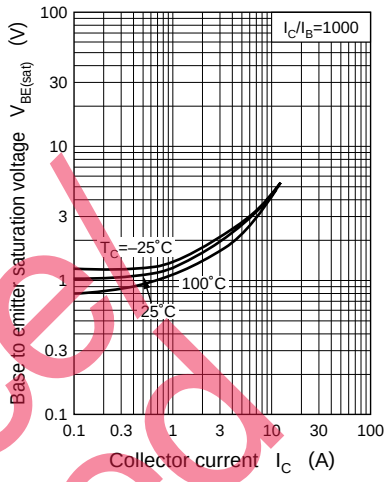
P_C — Ta



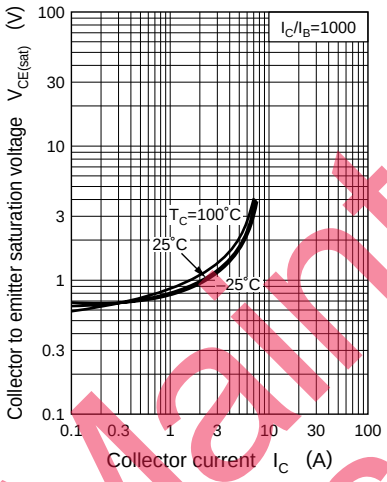
I_C — V_{CE}



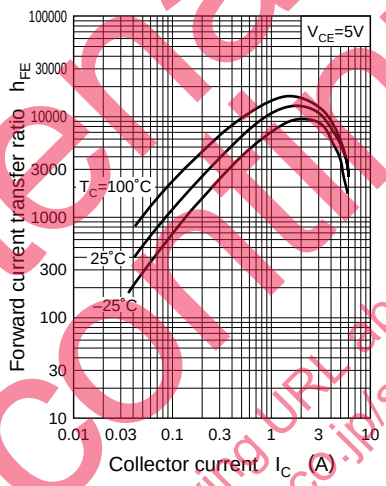
$V_{BE(sat)}$ — I_C



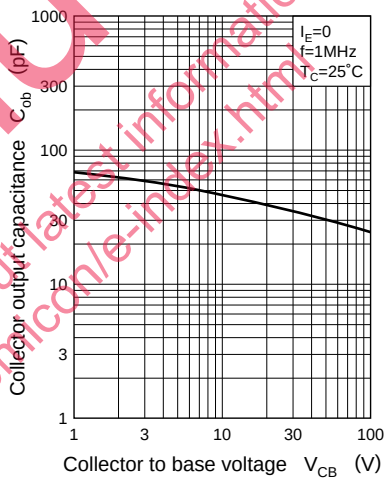
$V_{CE(sat)}$ — I_C



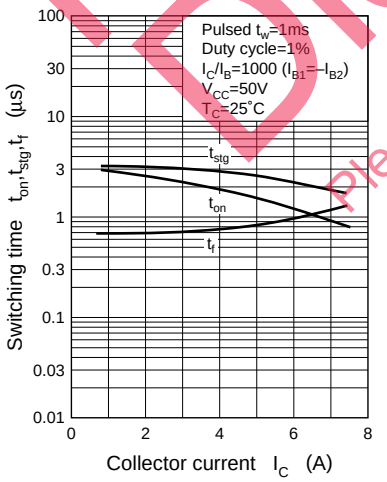
h_{FE} — I_C



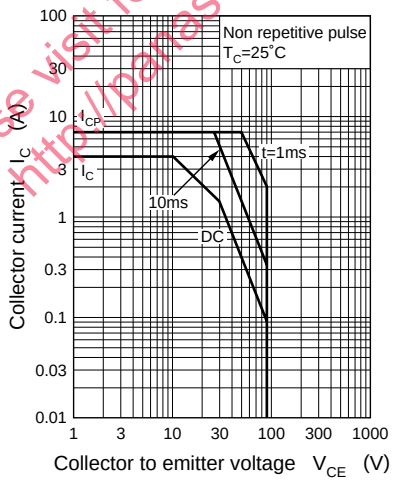
C_{ob} — V_{CB}



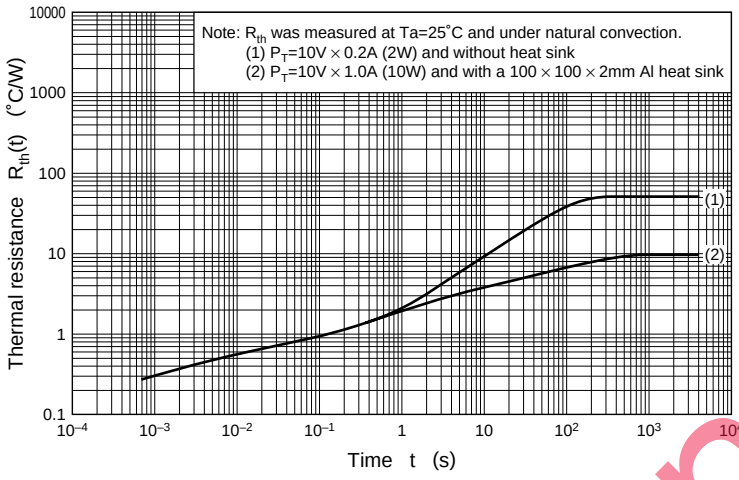
t_{on}, t_{stg}, t_f — I_C



Area of safe operation (ASO)



$R_{th(t)}$ — t



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